that in the present application, Applicants are claiming priority to prior application no. 09/403,741, which itself was filed under 35 U.S.C. § 371 as the national stage of international application No. PCT/FR99/00467, which in turn also claimed priority to French application No. 98 02493. Applicants have amended the specification to clearly set forth this claim to priority. Acknowledgment of the claims to priority in the present application is requested.

Claims 1-6, 14 and 15 were rejected under 35 U.S.C. § 102(a or e) as being anticipated by, or in the alternative, under 35 U.S.C. § 103(a) as obvious, in part over U.S. Patent No. 6,054,401 to Sugiura *et al.* ("Sugiura") and U.S. Patent No. 5,990,023 to Siedel *et al.* ("Siedel"), each taken alone.

Sugiura and Siedel are not prior art to the present application. The present application has a PCT international filing date of March 2, 1999, and claims priority to French application no. 98/02493, filed March 2, 1998. Thus, the rejection based on Sugiura and Siedel should be withdrawn. *See* 35 U.S.C. §§ 119, 365. Applicants have submitted herewith a translation of French application No. 98 02493, from which priority is being claimed in this application, attached hereto as Exhibit C, along with a certified copy thereof, attached-hereto-as-Exhibit-D.

With respect to the remaining rejections over U.S. Patent No. 5,858,897 to Maeda et al., U.S. Patent No. 5,362,689 to Morimoto et al., and U.S. Patent No. 5,618,763 to Frank et al., applicants incorporate herein the arguments previously presented in an Amendment dated October 28, 2002.

A Notice of Appeal is being filed concurrently herewith.

A fee for an extension of time is believed to be due for this submission and a petition for extension of time is submitted concurrently herewith. Should any additional fees be required, please charge such fees to Pennie & Edmonds LLP Deposit Account No. 16-1150.

Date: March 26, 2003

san a.a.

Respectfully Submitted,

Seth A. Watkins

Reg. No. 47,169

For: Victor N. Balancia

Reg. No. 31,231

PENNIE & EDMONDS LLP

1667 K Street, N.W.

Washington, D.C. 20006

(202) 496-4400

Enclosures

## **PCT**

## ORGANISATION MONDIALE DE LA PROPRIETE INTELLECTUELLE Bureau international



## DEMANDE INTERNATIONALE PUBLIEE EN VERTU DU TRAITE DE COOPERATION EN MATIERE DE BREVETS (PCT)

(51) Classification internationale des brevets <sup>6</sup>:

C03C 3/087

(11) Numéro de publication internationale: WO 99/44952

(43) Date de publication internationale: 10 septembre 1999 (10.09.99)

(21) Numéro de la demande internationale: PCT/FR99/00467

(22) Date de dépôt international: 2 mars 1999 (02.03.99)

(30) Données relatives à la priorité: 98/02493 2 mars 1998 (02.03.98) FR

(71) Déposant (pour tous les Etats désignés sauf US): SAINT-GOBAIN VITRAGE [FR/FR]; 18, avenue d'Alsace. F-92400 Courbevoie (FR).

(72) Inventeurs; et (75) Inventeurs/Déposants (US seulement): BORDEAUX, Frédéric [FR/FR]; 7, avenue Galois, F-92340 Bourg la Reine (FR).

DUFFRENE, Lucas [FR/FR]; 131, rue Legendre, F-75017 Paris (FR).

(74) Mandataires: LE CAM, Stéphane etc.; Saint-Gobain Recherche, 39, quai Lucien Lefranc, F-93300 Aubervilliers

(81) Etats désignés: JP, KR, US, brevet européen (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

Publiée

Avec rapport de recherche internationale.

(54) Title: GLASS SHEET DESIGNED TO BE HEAT TEMPERED

(54) Titre: FEUILLE DE VERRE DESTINEE A ETRE TREMPEE THERMIQUEMENT

(57) Abstract

The invention concerns a glass sheet designed to be heat tempered whereof the matrix is of silico-codo-calcic type, having an coefficient of expansion  $\alpha$  higher than  $100.10^{-7}$  K<sup>-1</sup>, a Young's modulus of expansion E higher than 60 Gpa and a thermal conductivity K less than 0.9 W/m.K.

(57) Abrégé

L'invention a pour objet une feuille de verre destinée à être trempée thermiquement dont la matrice est du type silico-sodo-calcique, présentant un coefficient de dilatation  $\alpha$  supérieur à  $100.10^{-7}$  K<sup>-1</sup>, un module d'Young E supérieur à 60 Gpa et une conductivité thermique K inférieure à 0.9 W/m.K.